Special Issue

Textiles Surface: Wearable and Smart Devices

Message from the Guest Editor

Wearable electronic devices have been attracting a lot of attention, with demand for portable and smart electronics continuing to increase. In particular, the use of electronic devices on textiles or fabrics makes it possible to implement a wearable electronic system without any additional attachment or embedding. The purpose of this Special Issue is to address advances in smart textile materials and fabric-based wearable devices. Research topics may include, but are not limited to, advanced materials, coatings, sensors, supercapacitors, and adhesion related to wearable devices. Research on various related topics, such as soft sensors, artificial skin, energy harvesting, supercapacitors, and filtration to implement wearable devices are also welcome in this Special Issue.

Guest Editor

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As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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